

**IN THE CLAIMS:**

1. – 11. Cancelled

12. (currently amended) The method of claim 1 ~~37~~, wherein testing at least one of the plurality of semiconductor die in the array further comprises testing in parallel at least two of the plurality of the semiconductor die.

13. (previously presented) A method for testing a plurality of semiconductor die, wherein the method comprises:

- providing a semiconductor wafer having a plurality of semiconductor die;
- singulating the semiconductor wafer;
- placing the plurality of semiconductor die directly on a temporary adhesive substrate;
- placing the plurality of semiconductor die with the temporary adhesive substrate on a testing platform;
- testing in parallel at least two of the plurality of semiconductor die; and
- removing the temporary adhesive substrate after testing.

14. (original) The method of claim 13, further comprising:

- attaching the plurality of semiconductor die to a package substrate; and
- electrically connecting at least one of the plurality of semiconductor die to the package substrate.

15. (previously presented) The method of claim 13, wherein singulating comprises electrically isolating the plurality of semiconductor die.

16. (original) The method of claim 15, further comprising singulating the plurality of semiconductor die to physically separate at least two semiconductor die of the plurality of semiconductor die from each other.

17. Cancelled

18. (original) The method of claim 13, further comprising providing a support structure in contact with the temporary adhesive substrate.
19. (original) The method of claim 13, further comprising sorting the plurality of semiconductor die, wherein removing the temporary adhesive substrate is performed while sorting the plurality of semiconductor die.
20. (original) The method of claim 13, further comprising forming an array using the plurality of semiconductor die prior to placing the plurality of semiconductor die on the temporary adhesive substrate.
21. (original) The method of claim 13, wherein placing the plurality of semiconductor die on the temporary adhesive substrate forms an array.
22. – 32. Cancelled
33. (previously presented) The method of claim 13, wherein singulating the semiconductor wafer is performed prior to placing the plurality of semiconductor die directly on the temporary adhesive substrate, wherein placing the plurality of semiconductor die directly on the temporary adhesive substrate comprises:  
    placing the plurality of singulated semiconductor die directly on the temporary adhesive substrate.
34. (previously presented) The method of claim 13, wherein singulating the semiconductor wafer is performed after placing the plurality of semiconductor die directly on the temporary adhesive substrate, wherein placing the plurality of semiconductor die directly on the temporary adhesive substrate comprises:  
    placing the semiconductor wafer directly on the temporary adhesive substrate.
35. (previously presented) The method of claim 34, wherein singulating the semiconductor wafer is performed using a partial saw process.

36. (previously presented) The method of claim 34, wherein singulating is performed while the semiconductor wafer is directly on the temporary adhesive substrate.
37. (previously presented) A method for testing a plurality of semiconductor die, wherein the method comprises:
- providing a plurality of semiconductor die;
  - encapsulating the plurality of semiconductor die to form an array, wherein the array has a perimeter;
  - placing the array on a temporary substrate;
  - electrically isolating the plurality of semiconductor die in the array using a partial saw process, the partial saw process leaving at least a portion of the encapsulation between at least two of the plurality of semiconductor devices;
  - placing the array with the temporary substrate on a testing platform;
  - testing at least one of the plurality of semiconductor die in the array while the array is on the temporary substrate and the testing platform; and
  - removing the temporary substrate.
38. (previously presented) The method of claim 37, further comprising:
- attaching the plurality of semiconductor die to a package substrate; and
  - electrically connecting at least one of the plurality of semiconductor die to the package substrate.
39. (previously presented) The method of claim 37, wherein electrically isolating is performed by using one of a saw and a laser.
40. (previously presented) The method of claim 37, further comprising, after testing, fully singulating the plurality of semiconductor die in the array to physically separate at least two semiconductor die of the plurality of semiconductor die from each other.
41. (previously presented) The method of claim 40, wherein singulating is performed by sawing.
42. (previously presented) The method of claim 37, wherein the temporary substrate is a temporary adhesive substrate.